# Advanced Micro Devices

# PALCE22V10 Family

## 24-Pin EE CMOS Versatile PAL Device

### **DISTINCTIVE CHARACTERISTICS**

- As fast as 5-ns propagation delay and 142.8 MHz f<sub>MAX</sub> (external)
- **■** Low-power EE CMOS
- 10 macrocells programmable as registered or combinatorial, and active high or active low to match application needs
- Varied product term distribution allows up to 16 product terms per output for complex functions
- Peripheral Component Interconnect (PCI) compliant (-5/-7/-10)

- Global asynchronous reset and synchronous preset for initialization
- Power-up reset for initialization and register preload for testability
- Extensive third-party software and programmer support through FusionPLD partners
- 24-pin SKINNYDIP, 24-pin SOIC, 24-pin Flatpack and 28-pin PLCC and LCC packages save space
- 5-ns and 7.5-ns versions utilize split leadframes for improved performance

#### **GENERAL DESCRIPTION**

The PALCE22V10 provides user-programmable logic for replacing conventional SSI/MSI gates and flip-flops at a reduced chip count.

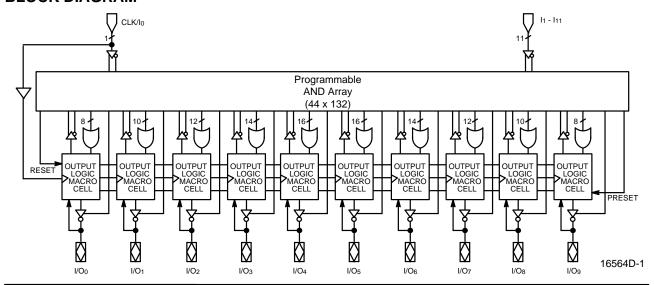
The PAL device implements the familiar Boolean logic transfer function, the sum of products. The PAL device is a programmable AND array driving a fixed OR array. The AND array is programmed to create custom product terms, while the OR array sums selected terms at the outputs.

The product terms are connected to the fixed OR array with a varied distribution from 8 to 16 across the outputs (see Block Diagram). The OR sum of the products feeds the output macrocell. Each macrocell can be programmed as registered or combinatorial, and active

high or active low. The output configuration is determined by two bits controlling two multiplexers in each macrocell.

AMD's FusionPLD program allows PALCE22V10 designs to be implemented using a wide variety of popular industry-standard design tools. By working closely with the FusionPLD partners, AMD certifies that the tools provide accurate, quality support. By ensuring that third-party tools are available, costs are lowered because a designer does not have to buy a complete set of new tools for each device. The FusionPLD program also greatly reduces design time since a designer can use a tool that is already installed and familiar.

#### **BLOCK DIAGRAM**



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## **CONNECTION DIAGRAMS**

# **Top View**

#### PLCC/LCC SKINNYDIP/SOIC/FLATPACK CLK/I<sub>0</sub> □ Vcc 24 23 1<sub>1</sub> L ∐ I/O9 3 2 I<sub>2</sub> [ 3 22 I I/O<sub>8</sub> 1/07 25 $I_3$ 21 l3 🛚 L 1/O7 $I_4$ 6 24 ∐ I/O<sub>6</sub> 14 20 J I/O<sub>6</sub> $I_5$ 23 I/O<sub>5</sub> 19 l5 L 6 I/O₅ NC 22 GND/NC\* l6 [ 8 18 I/O₄ $I_6$ 21 $I/O_4$ 17 9 l7 [ 8 I/O<sub>3</sub> l8 [ ] <sub>I/O2</sub> 9 16 10 20 $I/O_3$ l9 [ 10 15 I/O<sub>1</sub> $I/O_2$ 19 I<sub>10</sub> □ I/O₀ 12 13 14 15 16 17 18 11 14 13 1<sub>11</sub> 12 GND GND

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#### Note:

Pin 1 is marked for orientation.

## **PIN DESIGNATIONS**

CLK = Clock GND = Ground

I = Input I/O = Input/

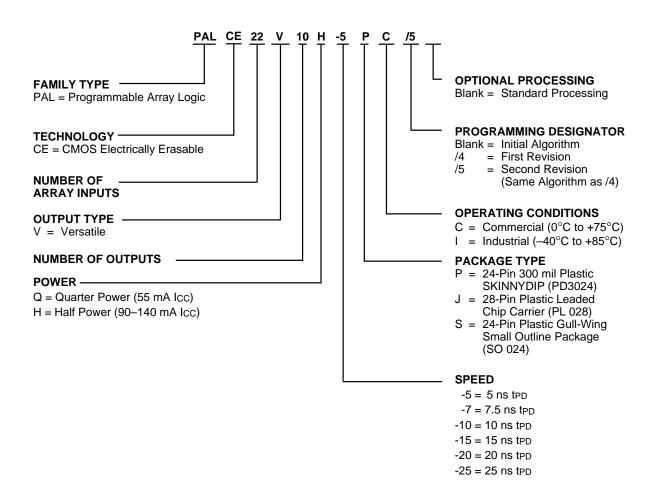
I/O = Input/Output
NC = No Connect
Vcc = Supply Voltage

<sup>\*</sup> For -5, this pin must be grounded for guaranteed data sheet performance. If not grounded, AC timing may degrade by about 10%.

#### ORDERING INFORMATION

#### **Commercial and Industrial Products**

AMD programmable logic products for commercial and industrial applications are available with several ordering options. The order number (Valid Combination) is formed by a combination of:



	Va		
	PALCE22V10-5	JC	
I	PALCE22V10H-7	PC, JC	/5
	PALCE22V10H-10	PC, JC, SC, PI, JI, ZC	/5
	PALCE22V10Q-10	PC, JC	
	PALCE22V10H-15	PC, JC, PI, JI, ZC	Blank, /5, /4
	PALCE22V10Q-15	PC, JC	/5
	PALCE22V10H-20	PI, JI	/4
I	PALCE22V10H-25	PC, JC, SC, PI, JI	Diami. /4
	PALCE22V10Q-25	PC, JC	Blank, /4

#### **Valid Combinations**

Valid Combinations lists configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations and to check on newly released combinations.

### **FUNCTIONAL DESCRIPTION**

The PALCE22V10 allows the systems engineer to implement the design on-chip, by programming EE cells to configure AND and OR gates within the device, according to the desired logic function. Complex interconnections between gates, which previously required timeconsuming layout, are lifted from the PC board and placed on silicon, where they can be easily modified during prototyping or production.

Product terms with all connections opened assume the logical HIGH state; product terms connected to both true and complement of any single input assume the logical LOW state.

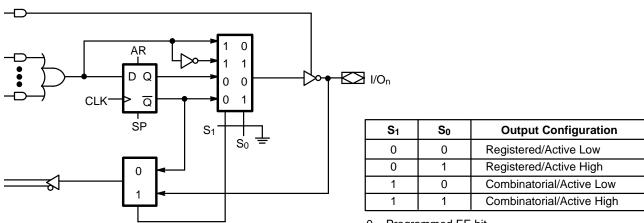
The PALCE22V10 has 12 inputs and 10 I/O macrocells. The macrocell (Figure 1) allows one of four potential output configurations; registered output or combinatorial I/O, active high or active low (see Figure 1). The configuration choice is made according to the user's design

specification and corresponding programming of the configuration bits  $S_0 - S_1$ . Multiplexer controls are connected to ground (0) through a programmable bit, selecting the "0" path through the multiplexer. Erasing the bit disconnects the control line from GND and it is driven to a high level, selecting the "1" path.

The device is produced with a EE cell link at each input to the AND gate array, and connections may be selectively removed by applying appropriate voltages to the circuit. Utilizing an easily-implemented programming algorithm, these products can be rapidly programmed to any customized pattern.

### Variable Input/Output Pin Ratio

The PALCE22V10 has twelve dedicated input lines, and each macrocell output can be an I/O pin. Buffers for device inputs have complementary outputs to provide user-programmable input signal polarity. Unused input pins should be tied to Vcc or GND.



0 = Programmed EE bit

1 = Erased (charged) EE bit

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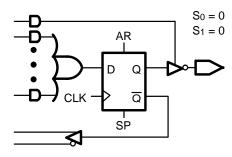
Figure 1. Output Logic Macrocell Diagram

# **Registered Output Configuration**

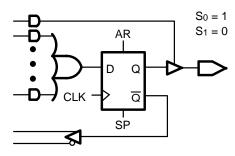
Each macrocell of the PALCE22V10 includes a D-type flip-flop for data storage and synchronization. The flip-flop is loaded on the LOW-to-HIGH transition of the clock input. In the registered configuration ( $S_1 = 0$ ), the array feedback is from  $\overline{\mathbb{Q}}$  of the flip-flop.

# **Combinatorial I/O Configuration**

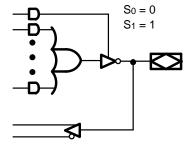
Any macrocell can be configured as combinatorial by selecting the multiplexer path that bypasses the flip-flop  $(S_1=1)$ . In the combinatorial configuration the feedback is from the pin.



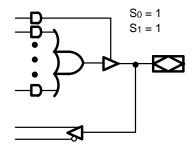
Registered/Active Low



Registered/Active High



Combinatorial/Active Low



Combinatorial/Active High

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**Figure 2. Macrocell Configuration Options** 



# **Programmable Three-State Outputs**

Each output has a three-state output buffer with three-state control. A product term controls the buffer, allowing enable and disable to be a function of any product of device inputs or output feedback. The combinatorial output provides a bidirectional I/O pin, and may be configured as a dedicated input if the buffer is always disabled.

## **Programmable Output Polarity**

The polarity of each macrocell output can be active high or active low, either to match output signal needs or to reduce product terms. Programmable polarity allows Boolean expressions to be written in their most compact form (true or inverted), and the output can still be of the desired polarity. It can also save "DeMorganizing" efforts.

Selection is controlled by programmable bit  $S_0$  in the output macrocell, and affects both registered and combinatorial outputs. Selection is automatic, based on the design specification and pin definitions. If the pin definition and output equation have the same polarity, the output is programmed to be active high ( $S_0 = 1$ ).

#### Preset/Reset

For initialization, the PALCE22V10 has Preset and Reset product terms. These terms are connected to all registered outputs. When the Synchronous Preset (SP) product term is asserted high, the output registers will be loaded with a HIGH on the next LOW-to-HIGH clock transition. When the Asynchronous Reset (AR) product term is asserted high, the output registers will be immediately loaded with a LOW independent of the clock.

Note that preset and reset control the flip-flop, not the output pin. The output level is determined by the output polarity selected.

### **Power-Up Reset**

All flip-flops power-up to a logic LOW for predictable system initialization. Outputs of the PALCE22V10 will depend on the programmed output polarity. The  $V_{\rm CC}$  rise must be monotonic and the reset delay time is 1000 ns maximum.

### **Register Preload**

The register on the PALCE22V10 can be preloaded from the output pins to facilitate functional testing of complex state machine designs. This feature allows

direct loading of arbitrary states, making it unnecessary to cycle through long test vector sequences to reach a desired state. In addition, transitions from illegal states can be verified by loading illegal states and observing proper recovery.

### **Security Bit**

After programming and verification, a PALCE22V10 design can be secured by programming the security EE bit. Once programmed, this bit defeats readback of the internal programmed pattern by a device programmer, securing proprietary designs from competitors. When the security bit is programmed, the array will read as if every bit is erased, and preload will be disabled.

The bit can only be erased in conjunction with erasure of the entire pattern.

## **Programming and Erasing**

The PALCE22V10 can be programmed on standard logic programmers. It also may be erased to reset a previously configured device back to its virgin state. Erasure is automatically performed by the programming hardware. No special erase operation is required.

## **Quality and Testability**

The PALCE22V10 offers a very high level of built-in quality. The erasability of the device provides a direct means of verifying performance of all AC and DC parameters. In addition, this verifies complete programmability and functionality of the device to provide the highest programming yields and post-programming functional yields in the industry.

# **Technology**

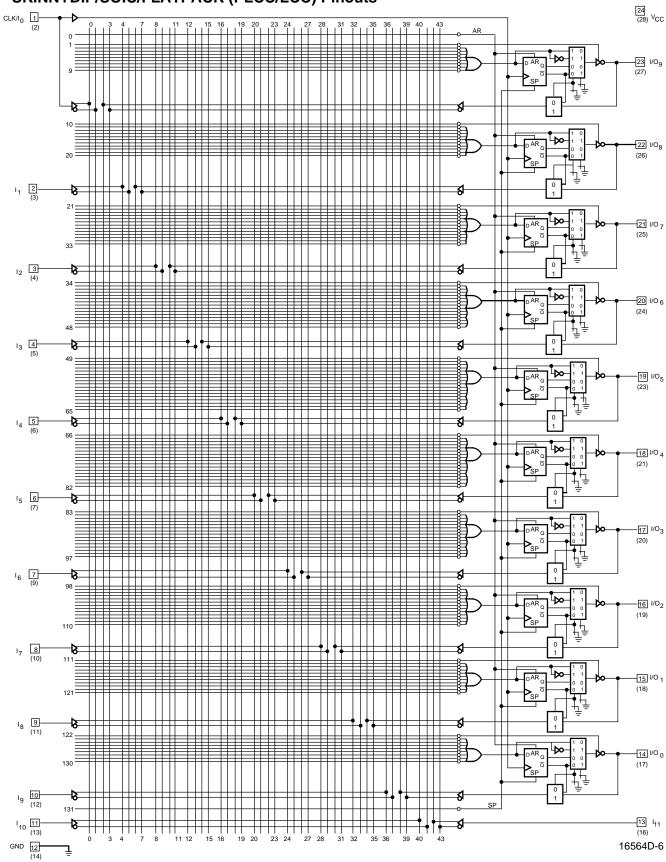
The high-speed PALCE22V10 is fabricated with AMD's advanced electrically erasable (EE) CMOS process. The array connections are formed with proven EE cells. Inputs and outputs are designed to be compatible with TTL devices. This technology provides strong input clamp diodes, output slew-rate control, and a grounded substrate for clear switching.

## **PCI Compliance**

The PALCE22V10H-5/7/10 is fully compliant with the *PCI Local Bus Specification* published by the PCI Special Interest Group. The PALCE22V10H-5/7/10's predictable timing ensures compliance with the PCI AC specifications independent of the design.

## **LOGIC DIAGRAM**

# SKINNYDIP/SOIC/FLATPACK (PLCC/LCC) Pinouts





Storage Temperature $\ \dots \ -65^{\circ}C$ to +150°C
Ambient Temperature with Power Applied55°C to +125°C
Supply Voltage with Respect
to Ground0.5 V to +7.0 V
DC Input Voltage $-0.5~V$ to $V_{CC}$ + 1.0 $V$
DC Output or I/O Pin
Voltage0.5 V to Vcc + 1.0 V
Static Discharge Voltage 2001 V
Latchup Current ( $T_A = 0$ °C to +75°C) 100 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

#### **OPERATING RANGES**

## Commercial (C) Devices

Ambient Temperature (T <sub>A</sub> ) Operating in Free Air	0°C to +75°C
Supply Voltage (Vcc) with Respect to Ground +4.79	5 V to +5.25 \

Operating Ranges define those limits between which the functionality of the device is guaranteed.

# DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Max	Unit
Voн	Output HIGH Voltage	IOH = -3.2  mA $VIN = VIH  or  VIL$ $VCC = Min$	2.4		V
VoL	Output LOW Voltage	IOL = 16 mA VIN = VIH or VIL VCC = Min		0.4	V
ViH	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0		V
VIL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)		0.8	>
Іін	Input HIGH Leakage Current	V <sub>IN</sub> = V <sub>CC</sub> , V <sub>CC</sub> = Max (Note 2)		10	μΑ
lı∟	Input LOW Leakage Current	V <sub>IN</sub> = 0 V, V <sub>CC</sub> = Max (Note 2)		-100	μΑ
Гоzн	Off-State Output Leakage Current HIGH	Vout = Vcc, Vcc = Max, Vin = ViL or ViH (Note 2)		10	μΑ
lozL	Off-State Output Leakage Current LOW	Vout = 0 V, Vcc = Max, V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> (Note 2)		-100	μΑ
Isc	Output Short-Circuit Current	Vout = 0.5 V, Vcc = Max (Note 3)	-30	-130	mA
I <sub>CC</sub> (Static)	Supply Current	Outputs Open, (I <sub>OUT</sub> = 0 mA), Vcc = Max		125	mA
lcc (Dynamic)	Supply Current	Outputs Open, (Iout = 0 mA), V <sub>CC</sub> = Max, f = 25 MHz		140	mA

- 1. These are absolute values with respect to the device ground and all overshoots due to system and tester noise are included.
- 2. I/O pin leakage is the worst case of I<sub>IL</sub> and I<sub>OZL</sub> (or I<sub>IH</sub> and I<sub>OZH</sub>).
- 3. Not more than one output should be tested at a time. Duration of the short-circuit test should not exceed one second.  $V_{OUT} = 0.5 \text{ V}$  has been chosen to avoid test problems caused by tester ground degradation.

Parameter Symbol	Parameter Description	Test Conditions		Тур	Unit
CIN	Input Capacitance	VIN = 2.0 V	Vcc = 5.0 V	5	
Соит	Output Capacitance	V <sub>OUT</sub> = 2.0 V	T <sub>A</sub> = 25°C f = 1 MHz	8	pF

#### Note:

# **SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2)**

Damamatan			{	5		
Parameter Symbol	Parameter Description			Min	Max	Unit
tPD	Input or Feedl	oack to Combinatorial Outpu		5	ns	
ts <sub>1</sub>	Setup Time from	om Input or Feedback		3		ns
t <sub>S2</sub>	Setup Time fro	om SP to Clock		4		ns
tн	Hold Time			0		ns
tco	Clock to Outp	ut			4	ns
tskewr	Skew Betwee	n Registered Outputs (Note	3)		0.5	ns
tar	Asynchronous	ynchronous Reset to Registered Output			7.5	ns
t <sub>ARW</sub>	Asynchronous	Reset Width		4.5		ns
tarr	Asynchronous	Reset Recovery Time		4.5		ns
tspr	Synchronous	Preset Recovery Time		4.5		ns
tw∟		LOW		2.5		ns
twH	Clock Width	HIGH		2.5		ns
	Maximum	External Feedback	1/(ts + tco)	142.8		MHz
fmax	Frequency	Internal Feedback (fcnt)	1/(ts + tcr) (Note 5)	150		MHz
	(Note 4)	No Feedback	1/(twh + twl)	200		MHz
tEA	Input to Outpu	Input to Output Enable Using Product Term Control			6	ns
tER	Input to Outpu	t Disable Using Product Ter	m Control		5.5	ns

- 2. See Switching Test Circuit for test conditions.
- 3. Skew is measured with all outputs switching in the same direction.
- 4. These parameters are not 100% tested, but are calculated at initial characterization and at any time the design is modified where frequency may be affected.
- 5.  $t_{CF}$  is a calculated value and is not guaranteed.  $t_{CF}$  can be found using the following equation:  $t_{CF} = 1/f_{MAX}$  (internal feedback)  $t_{S}$ .

<sup>1.</sup> These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.



Storage Temperature65°C to +150°C
Ambient Temperature with Power Applied55°C to +125°C
Supply Voltage with Respect
to Ground0.5 V to +7.0 V
DC Input Voltage $-0.5~V$ to $V_{CC}$ + 1.0 $V$
DC Output or I/O Pin
Voltage0.5 V to Vcc + 1.0 V
Static Discharge Voltage 2001 V
Latchup Current ( $T_A = 0$ °C to +75°C) 100 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

#### **OPERATING RANGES**

## Commercial (C) Devices

Ambient Temperature (T <sub>A</sub> )	
Operating in Free Air	0°C to +75°C
Supply Voltage (Vcc) with	
Respect to Ground +4.7	5 V to +5.25 V

Operating Ranges define those limits between which the functionality of the device is guaranteed.

# DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Max	Unit
Voн	Output HIGH Voltage	$I_{OH} = -3.2 \text{ mA}$ $V_{IN} = V_{IH} \text{ or } V_{IL}$ $V_{CC} = Min$	2.4		V
Vol	Output LOW Voltage	IoL = 16 mA VIN = VIH or VIL VCC = Min		0.4	V
Vih	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0		V
VIL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)		0.8	V
Іін	Input HIGH Leakage Current	VIN = Vcc, Vcc = Max (Note 2)		10	μΑ
IιL	Input LOW Leakage Current	V <sub>IN</sub> = 0 V, V <sub>CC</sub> = Max (Note 2)		-100	μΑ
Іоzн	Off-State Output Leakage Current HIGH	Vout = Vcc, Vcc = Max, Vin = Vil or Vih (Note 2)		10	μА
lozL	Off-State Output Leakage Current LOW	Vout = 0 V, Vcc = Max, Vin = ViL or ViH (Note 2)		-100	μА
Isc	Output Short-Circuit Current	V <sub>OUT</sub> = 0.5 V, V <sub>CC</sub> = Max T <sub>A</sub> = 25°C (Note 3)	-30	-130	mA
Icc (Static)	Supply Current	Outputs Open, (IouT = 0 mA), Vcc = Max		115	mA
Icc (Dynamic)	Supply Current	Outputs Open, (I <sub>OUT</sub> = 0 mA), Vcc = Max, f = 25 MHz		140	mA

- 1. These are absolute values with respect to the device ground and all overshoots due to system and tester noise are included.
- 2. I/O pin leakage is the worst case of I<sub>IL</sub> and I<sub>OZL</sub> (or I<sub>IH</sub> and I<sub>OZH</sub>).
- 3. Not more than one output should be tested at a time. Duration of the short-circuit test should not exceed one second.  $V_{OUT} = 0.5 \text{ V}$  has been chosen to avoid test problems caused by tester ground degradation.

Parameter Symbol	Parameter Description	Test Conditions		Тур	Unit
Cin	Input Capacitance	VIN = 2.0 V	Vcc = 5.0 V	5	
Соит	Output Capacitance	V <sub>OUT</sub> = 2.0 V	T <sub>A</sub> = 25°C f = 1 MHz	8	pF

#### Note:

# **SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2)**

					7			
Parameter			PI	OIP	PL	CC		
Symbol	Parameter De	escription		Min	Max	Min	Max	Unit
t <sub>PD</sub>	Input or Feedback to Combinatorial Output			3	7.5	3	7.5	ns
ts1	Setup Time fro	om Input or Feedback		5		4.5		ns
t <sub>S2</sub>	Setup Time from	om SP to Clock		6		6		ns
tн	Hold Time			0		0		ns
tco	Clock to Outpo	ut		2	5	2	4.5	ns
tskewr	Skew Between	n Registered Outputs (Note	3)		1		1	ns
tar	Asynchronous	Reset to Registered Outpu	t		10		10	ns
tarw	Asynchronous	Reset Width		7		7		ns
tarr	Asynchronous	Reset Recovery Time		7		7		ns
tspr	Synchronous	Preset Recovery Time		7		7		ns
t <sub>W</sub> ∟	Classic W/Saltha	LOW		3.5		3.0		ns
twH	Clock Width	HIGH		3.5		3.0		ns
	Maximum	External Feedback	1/(ts + tco)	100		111		MHz
fmax	Frequency	Internal Feedback (fcnt)	1/(ts + tcr) (Note 5)	125		133		MHz
	(Note 4)	No Feedback	1/(t <sub>WH</sub> + t <sub>WL</sub> )	142.8		166		MHz
tEA	Input to Output Enable Using Product Term Control				7.5		7.5	ns
t <sub>ER</sub>	Input to Outpu	t Disable Using Product Ter	m Control		7.5		7.5	ns

- 2. See Switching Test Circuit for test conditions.
- 3. Skew is measured with all outputs switching in the same direction.
- 4. These parameters are not 100% tested, but are calculated at initial characterization and at any time the design is modified where frequency may be affected.
- 5.  $t_{CF}$  is a calculated value and is not guaranteed.  $t_{CF}$  can be found using the following equation:  $t_{CF} = 1/f_{MAX}$  (internal feedback)  $t_{S}$ .

<sup>1.</sup> These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.



Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

#### **OPERATING RANGES**

## Commercial (C) Devices

Ambient Temperature (T<sub>A</sub>)
Operating in Free Air ..... 0°C to +75°C
Supply Voltage (Vcc) with
Respect to Ground ..... +4.75 V to +5.25 V

Operating Ranges define those limits between which the functionality of the device is guaranteed.

# DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Max	Unit
Voн	Output HIGH Voltage	IOH = -3.2  mA $VIN = VIH  or VIL$ $VCC = Min$	2.4		V
VoL	Output LOW Voltage	$I_{OL} = 16 \text{ mA}$ $V_{IN} = V_{IH} \text{ or } V_{IL}$ $V_{CC} = \text{Min}$		0.4	V
ViH	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0		V
VIL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)		0.8	V
lін	Input HIGH Leakage Current	V <sub>IN</sub> = V <sub>CC</sub> , V <sub>CC</sub> = Max (Note 2)		10	μΑ
IιL	Input LOW Leakage Current	V <sub>IN</sub> = 0 V, V <sub>CC</sub> = Max (Note 2)		-100	μΑ
Іоzн	Off-State Output Leakage Current HIGH	Vout = Vcc, Vcc = Max, V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> (Note 2)		10	μА
lozL	Off-State Output Leakage Current LOW	Vout = 0 V, Vcc = Max Vin = ViL or ViH (Note 2)		-100	μА
Isc	Output Short-Circuit Current	Vout = 0.5 V, Vcc = Max T <sub>A</sub> = 25° C (Note 3)	-30	-130	mA
lcc (Dynamic)	Supply Current	Outputs Open, (Iout = 0 mA), V <sub>CC</sub> = Max, f = 25 MHz		120	mA

- 1. These are absolute values with respect to the device ground and all overshoots due to system and tester noise are included.
- 2. I/O pin leakage is the worst case of IIL and IOZL (or IIH and IOZH).
- 3. Not more than one output should be tested at a time. Duration of the short-circuit test should not exceed one second.  $V_{OUT} = 0.5 \text{ V}$  has been chosen to avoid test problems caused by tester ground degradation.

Parameter Symbol	Parameter Description	Test Conditions		Тур	Unit
Cin	Input Capacitance	V <sub>IN</sub> = 2.0 V	Vcc = 5.0 V	5	
Соит	Output Capacitance	V <sub>OUT</sub> = 2.0 V	T <sub>A</sub> = 25°C f = 1 MHz	8	pF

#### Note:

# **SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2)**

Parameter					10	
Symbol	Parameter De	escription		Min	Max	Unit
tPD	Input or Feedback to Combinatorial Output		ıt		10	ns
ts1	Setup Time fro	om Input or Feedback		6		ns
ts2	Setup Time fro	om SP to Clock		7		ns
tн	Hold Time			0		ns
tco	Clock to Outpu	ut			6	ns
t <sub>AR</sub>	Asynchronous	synchronous Reset to Registered Output			13	ns
tarw	Asynchronous Reset Width			8		ns
tarr	Asynchronous Reset Recovery Time			8		ns
tspr	Synchronous I	chronous Preset Recovery Time				ns
t <sub>WL</sub>	01 1 147 141	LOW		4		ns
twH	Clock Width	HIGH		4		ns
	Maximum	External Feedback	1/(t <sub>S</sub> + t <sub>CO</sub> )	83.3		MHz
fmax	Frequency	Internal Feedback (fcnt)	1/(ts + tcr) (Note 4)	110		MHz
	(Note 3)	No Feedback 1/(t <sub>WH</sub> + t <sub>WL</sub> )		125		MHz
tEA	Input to Output Enable Using Product Term Control			10	ns	
tER	Input to Outpu	t Disable Using Product Ter	m Control		9	ns

- 2. See Switching Test Circuit for test conditions.
- 3. These parameters are not 100% tested, but are calculated at initial characterization and at any time the design is modified where frequency may be affected.
- 4.  $t_{CF}$  is a calculated value and is not guaranteed.  $t_{CF}$  can be found using the following equation:  $t_{CF} = 1/f_{MAX}$  (internal feedback)  $t_{S}$ .

<sup>1.</sup> These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.



Storage Temperature $\ \dots \ -65^{\circ}C \ $ to $+150^{\circ}C$
Ambient Temperature with Power Applied55°C to +125°C
Supply Voltage with Respect
to Ground
DC Input Voltage $-0.5~V$ to Vcc + 1.0 V
DC Output or I/O Pin
Voltage0.5 V to Vcc + 1.0 V
Static Discharge Voltage 2001 V
Latchup Current ( $T_A = 0^{\circ}C$ to +75°C) 100 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

#### **OPERATING RANGES**

tionality of the device is guaranteed.

## Commercial (C) Devices

Operating in Free Air	0°C to +75°C
Supply Voltage (V <sub>CC</sub> ) with Respect to Ground	+4.75 V to +5.25 V
Operating Ranges define those limits	s between which the func-

# DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Max	Unit
Voн	Output HIGH Voltage	IOH = -3.2  mA $VIN = VIH  or  VIL$ $VCC = Min$	2.4		V
VoL	Output LOW Voltage	IOL = 16 mA VIN = VIH or VIL VCC = Min		0.4	V
ViH	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0		V
VIL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)		0.8	V
Іін	Input HIGH Leakage Current	V <sub>IN</sub> = V <sub>CC</sub> , V <sub>CC</sub> = Max (Note 2)		10	μΑ
lı∟	Input LOW Leakage Current	V <sub>IN</sub> = 0 V, V <sub>CC</sub> = Max (Note 2)		-100	μΑ
Іоzн	Off-State Output Leakage Current HIGH	Vout = Vcc, Vcc = Max Vin = ViL or ViH (Note 2)		10	μА
lozL	Off-State Output Leakage Current LOW	V <sub>OUT</sub> = 0 V, V <sub>CC</sub> = Max V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> (Note 2)		-100	μА
Isc	Output Short-Circuit Current	Vout = 0.5 V, Vcc = 5 V T <sub>A</sub> = 25°C (Note 3)	-30	-130	mA
I <sub>CC</sub> (Static)	Supply Current	V <sub>IN</sub> = 0 V, Outputs Open (I <sub>OUT</sub> = 0 mA), V <sub>CC</sub> = Max (Note 4)		55	mA

- 1. These are absolute values with respect to the device ground and all overshoots due to system and tester noise are included.
- 2. I/O pin leakage is the worst case of  $I_{IL}$  and  $I_{OZL}$  (or  $I_{IH}$  and  $I_{OZH}$ ).
- 3. Not more than one output should be tested at a time. Duration of the short-circuit test should not exceed one second.  $V_{OUT} = 0.5 \text{ V}$  has been chosen to avoid test problems caused by tester ground degradation.
- 4. This parameter is guaranteed worst case under test condition. Refer to the I<sub>CC</sub> vs. frequency graph for typical I<sub>CC</sub> characteristics.

Parameter Symbol	Parameter Description	Test Conditions		Тур	Unit
CIN	Input Capacitance	VIN = 2.0 V	Vcc = 5.0 V	5	ρF
Соит	Output Capacitance	Vout = 2.0 V	T <sub>A</sub> = 25°C f = 1 MHz	8	рΓ

#### Note:

# **SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2)**

Danamatan				^	0	
Parameter Symbol	Parameter De	escription		Min	Max	Unit
t <sub>PD</sub>	Input or Feedback to Combinatorial Output		ıt		10	ns
ts	Setup Time fro	om Input, Feedback or SP to	o Clock	6		ns
tн	Hold Time			0		ns
tco	Clock to Outpo	ut			6	ns
tar	Asynchronous	synchronous Reset to Registered Output			13	ns
tarw	Asynchronous	Asynchronous Reset Width				ns
t <sub>ARR</sub>	Asynchronous Reset Recovery Time			8		ns
tspr	Synchronous Preset Recovery Time			8		ns
tw∟		LOW		4		ns
twн	Clock Width	HIGH		4		ns
	Maximum	External Feedback	1/(ts + tco)	83		MHz
f <sub>MAX</sub>	Frequency	Internal Feedback (f <sub>CNT</sub> )	1/(t <sub>S</sub> + t <sub>CO</sub> ) (Note 4)	110		MHz
	(Note 3)	No Feedback	1/(twh + twl)	125		MHz
tEA	Input to Output Enable Using Product Term Control			10	ns	
ter	Input to Outpu	it Disable Using Product Ter	rm Control		9	ns

- 2. See Switching Test Circuit for test conditions.
- 3. These parameters are not 100% tested, but are calculated at initial characterization and at any time the design is modified where frequency may be affected.
- 4.  $t_{CF}$  is a calculated value and is not guaranteed.  $t_{CF}$  can be found using the following equation:  $t_{CF} = 1/f_{MAX}$  (internal feedback)  $t_{S}$ .

<sup>1.</sup> These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.



Storage Temperature .....  $-65^{\circ}$ C to +150°C Ambient Temperature with Power Applied .....  $-55^{\circ}$ C to +125°C Supply Voltage with Respect to Ground ..... -0.5 V to +7.0 V DC Input Voltage ..... -0.5 V to  $V_{CC}$  + 0.5 V DC Output or I/O Pin Voltage ..... -0.5 V to  $V_{CC}$  + 0.5 V Static Discharge Voltage ..... 2001 V Latchup Current ( $T_A$  = 0°C to +75°C) ..... 100 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

#### **OPERATING RANGES**

#### Commercial (C) Devices

Ambient Temperature ( $T_A$ )
Operating in Free Air ..... 0°C to +75°C
Supply Voltage ( $V_{CC}$ ) with
Respect to Ground (H/Q-15) .... +4.75 V to +5.25 V
Supply Voltage ( $V_{CC}$ ) with
Respect to Ground (H/Q-25) .... +4.5 V to +5.5 V

Operating Ranges define those limits between which the functionality of the device is guaranteed.

# DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Max	Unit
Voн	Output HIGH Voltage	IOH = -3.2 mA VIN = VIH or VIL VCC = Min	2.4		V
VoL	Output LOW Voltage	IOL = 16 mA VIN = VIH or VIL VCC = Min		0.4	٧
ViH	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0		V
VIL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)		0.8	٧
Іін	Input HIGH Leakage Current	VIN = Vcc, Vcc = Max (Note 2)		10	μΑ
I <sub>IL</sub>	Input LOW Leakage Current	V <sub>IN</sub> = 0 V, V <sub>CC</sub> = Max (Note 2)		-100	μΑ
lozh	Off-State Output Leakage Current HIGH	Vout = Vcc, Vcc = Max, Vin = ViL or ViH (Note 2)		10	μΑ
l <sub>OZL</sub>	Off-State Output Leakage Current LOW	V <sub>OUT</sub> = 0 V, V <sub>CC</sub> = Max, V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> (Note 2)		-100	μΑ
Isc	Output Short-Circuit Current	V <sub>OUT</sub> = 0.5 V, V <sub>CC</sub> = 5 V T <sub>A</sub> = 25°C (Note 3)	-30	-130	mA
Icc	Supply Current	VIN = 0 V, Outputs Open         H           (IOUT = 0 mA), Vcc = Max         Q		90 55	mA

- 1. These are absolute values with respect to the device ground and all overshoots due to system and tester noise are included.
- 2. I/O pin leakage is the worst case of I<sub>IL</sub> and I<sub>OZL</sub> (or I<sub>IH</sub> and I<sub>OZH</sub>).
- 3. Not more than one output should be tested at a time. Duration of the short-circuit test should not exceed one second. Vout = 0.5 V has been chosen to avoid test problems caused by tester ground degradation.

Parameter Symbol	Parameter Description	Test Conditions		Тур	Unit
C <sub>IN</sub>	Input Capacitance	V <sub>IN</sub> = 2.0 V	V <sub>CC</sub> = 5.0 V T <sub>A</sub> = 25°C	5	1
Соит	Output Capacitance	Vout = 2.0 V	f = 1 MHz	8	pF

#### Note:

# **SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2)**

			-19	5	-2	5		
Parameter Symbol	Parameter De	escription		Min	Max	Min	Max	Unit
t <sub>PD</sub>	Input or Feedb	pack to Combinatorial Output	t		15		25	ns
ts	Setup Time fro	om Input, Feedback or SP to	Clock	10		15		ns
tн	Hold Time			0		0		ns
tco	Clock to Outpu	ut			10		15	ns
tar	Asynchronous	Reset to Registered Output			20		25	ns
tarw	Asynchronous	nchronous Reset Width		15		25		ns
t <sub>ARR</sub>	Asynchronous Reset Recovery Time		10		25		ns	
tspr	Synchronous I	ous Preset Recovery Time		10		25		ns
tw∟	Clast Middle	LOW		8		13		ns
twн	Clock Width	HIGH		8		13		ns
f <sub>MAX</sub>	Maximum	External Feedback	1/(ts + tco)	50		33.3		MHz
	Frequency (Note 3)	Internal Feedback (f <sub>CNT</sub> )	1/(ts + t <sub>CF</sub> ) (Note 4)	58.8		35.7		MHz
t <sub>EA</sub>	Input to Outpu	Input to Output Enable Using Product Term Control			15		25	ns
ter	Input to Outpu	t to Output Disable Using Product Term Control			15		25	ns

- 2. See Switching Test Circuit for test conditions.
- 3. These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where frequency may be affected.
- 4.  $t_{CF}$  is a calculated value and is not guaranteed.  $t_{CF}$  can be found using the following equation:  $t_{CF} = 1/f_{MAX}$  (internal feedback)  $t_{S}$ .

<sup>1.</sup> These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.



Storage Temperature $\ \dots \ -65^{\circ}C$ to +150°C
Ambient Temperature with Power Applied55°C to +125°C
Supply Voltage with Respect
to Ground
DC Input Voltage $$ 0.5 V to V <sub>CC</sub> + 0.5 V
DC Output or I/O Pin
Voltage0.5 V to Vcc + 0.5 V
Static Discharge Voltage 2001 V
Latchup Current ( $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ ) 100 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

#### **OPERATING RANGES**

### Industrial (I) Devices

Ambient Temperature (T<sub>A</sub>)
Operating in Free Air ..... -40°C to +85°C
Supply Voltage (Vcc) with
Respect to Ground ..... +4.5 V to +5.5 V

Operating Ranges define those limits between which the functionality of the device is guaranteed.

# DC CHARACTERISTICS over INDUSTRIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Descript	ion	Test Conditions		Min	Max	Unit
Voн	Output HIGH Voltage	9	lон = −3.2 mA	$I_{OH} = -3.2 \text{ mA}$ $V_{IN} = V_{IH} \text{ or } V_{IL}$ $V_{CC} = Min$			V
VoL	Output LOW Voltage		I <sub>OL</sub> = 16 mA	IOL = 16 mA VIN = VIH or VIL VCC = Min		0.4	V
ViH	Input HIGH Voltage		Guaranteed Inpo Voltage for all In		2.0		V
VIL	Input LOW Voltage			Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)		0.8	V
Іін	Input HIGH Leakage	Current	VIN = VCC, VCC :	V <sub>IN</sub> = V <sub>CC</sub> , V <sub>CC</sub> = Max (Note 2)		10	μΑ
IιL	Input LOW Leakage	Current	V <sub>IN</sub> = 0 V, V <sub>CC</sub> = Max (Note 2)			-100	μΑ
Іоzн	Off-State Output Lea Current HIGH	kage	VOUT = VCC, VC	,		10	μА
lozL	Off-State Output Lea Current LOW	kage	1 00 , 00	Vout = 0 V, Vcc = Max, VIN = VIL or VIH (Note 2)		-100	μΑ
Isc	Output Short-Circuit Current		V <sub>OUT</sub> = 0.5 V, V <sub>CC</sub> = 5 V T <sub>A</sub> = 25°C (Note 3)		-30	-130	mA
I <sub>CC</sub> (Static)	Supply Current	H-20/25 H-10/15	V <sub>IN</sub> = 0 V, Outputs Open (Iout = 0 mA), Vcc = Max			100 110	mA
Icc (Dynamic)	Supply Current		VIN = 0 V, Outpu (IOUT = 0 mA), V	its Open /cc = Max, f = 15 MHz		130	mA

- 1. These are absolute values with respect to the device ground and all overshoots due to system and tester noise are included.
- 2. I/O pin leakage is the worst case of I<sub>IL</sub> and I<sub>OZL</sub> (or I<sub>IH</sub> and I<sub>OZH</sub>).
- 3. Not more than one output should be tested at a time. Duration of the short-circuit test should not exceed one second. Vout = 0.5 V has been chosen to avoid test problems caused by tester ground degradation.

Parameter Symbol	Parameter Description	Test Conditions		Тур	Unit
CIN	Input Capacitance	V <sub>IN</sub> = 2.0 V	Vcc = 5.0 V Ta = 25°C	5	יר
Соит	Output Capacitance	V <sub>OUT</sub> = 2.0 V	f = 1 MHz	8	pF

#### Note:

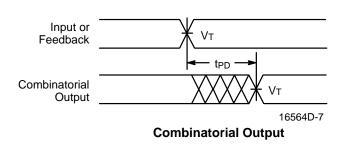
# **SWITCHING CHARACTERISTICS over INDUSTRIAL operating ranges (Note 2)**

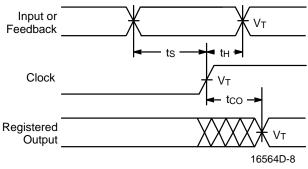
Parameter	er e		-1	0	-1	15	-2	20	-2	25		
Symbol	Parameter D	escription		Min	Max	Min	Max	Min	Max	Min	Max	Unit
tpD	Input or Feedback to Combinatorial Output			10		15		20		25	ns	
ts	Setup Time f	rom Input, Feedback o	or SP to Clock	7		10		12		15		ns
tн	Hold Time			0		0		0		0		ns
tco	Clock to Outp	out			6		10		12		15	ns
tar	Asynchronou	s Reset to Registered	Output		13		20		25		25	ns
tarw	Asynchronou	s Reset Width		8		15		20		25		ns
tarr	Asynchronou	us Reset Recovery Time		8		10		20		25		ns
tspr	Synchronous	us Preset Recovery Time		8			10		14	25		ns
tw∟	Clock Width	LOW		4		8		10		13		ns
twн	Clock Width	HIGH		4		8		10		13		ns
	Maximum	External Feedback	1/(ts + tco)	83.3		50		41.6		33.3		MHz
f <sub>MAX</sub>	Frequency (Note 3)	Internal Feedback (fcnt)	1/(t <sub>S</sub> + t <sub>CF</sub> ) (Note 4)	110		58.8		45.4		35.7		MHz
		No Feedback	1/(twh + twL)	125		83.3		50		38.5		MHz
tEA	Input to Output Enable Using Product Term Control			10		15		20		25	ns	
ter	Input to Outp Term Control	ut Disable Using Prod	uct		9		15		20		25	ns

- 2. See Switching Test Circuit for test conditions.
- 3. These parameters are not 100% tested, but are calculated at initial characterization and at any time the design is modified where frequency may be affected.
- 4.  $t_{CF}$  is a calculated value and is not guaranteed.  $t_{CF}$  can be found using the following equation:  $t_{CF} = 1/f_{MAX}$  (internal feedback)  $t_{S}$ .

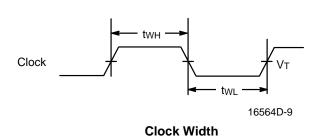
<sup>1.</sup> These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.

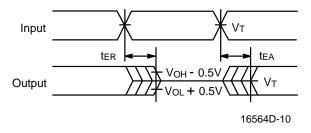
## **SWITCHING WAVEFORMS**



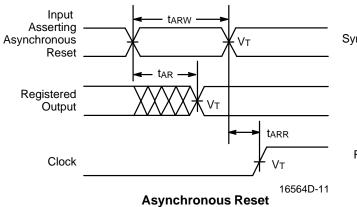


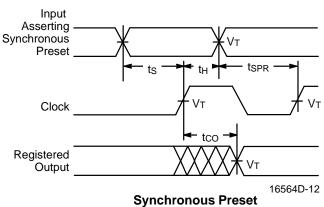
**Registered Output** 





Input to Output Disable/Enable





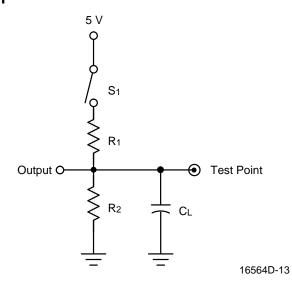
- 1.  $V_T = 1.5 V$ .
- 2. Input pulse amplitude 0 V to 3.0 V.
- 3. Input rise and fall times 2 ns 5 ns typical.

# **KEY TO SWITCHING WAVEFORMS**

WAVEFORM	INPUTS	OUTPUTS
	Must be Steady	Will be Steady
	May Change from H to L	Will be Changing from H to L
	May Change from L to H	Will be Changing from L to H
	Don't Care, Any Change Permitted	Changing, State Unknown
$\longrightarrow \longleftarrow$	Does Not Apply	Center Line is High- Impedance "Off" State

KS000010-PAL

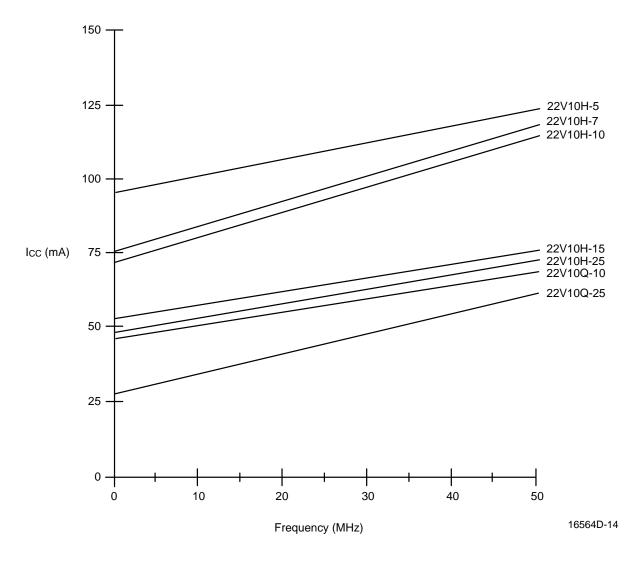
# **SWITCHING TEST CIRCUIT**



			Comi	mercial	Measured
Specification	S <sub>1</sub>	CL	R <sub>1</sub> R <sub>2</sub>		Output Value
t <sub>PD</sub> , t <sub>CO</sub>	Closed			All except H-5/7:	1.5 V
tea	$Z \rightarrow H$ : Open $Z \rightarrow L$ : Closed	50 pF	300 Ω	390 Ω	1.5 V
t <sub>ER</sub>	$H \rightarrow Z$ : Open $L \rightarrow Z$ : Closed	5 pF		H-5/7: 300 Ω	$H \rightarrow Z$ : $V_{OH} - 0.5 V$ $L \rightarrow Z$ : $V_{OL} + 0.5 V$

# TYPICAL Icc CHARACTERISTICS

 $V_{CC} = 5.0 \text{ V}, T_A = 25^{\circ}\text{C}$ 



Icc vs. Frequency

The selected "typical" pattern utilized 50% of the device resources. Half of the macrocells were programmed as registered, and the other half were programmed as combinatorial. Half of the available product terms were used for each macrocell. On any vector, half of the outputs were switching.

By utilizing 50% of the device, a midpoint is defined for  $I_{CC}$ . From this midpoint, a designer may scale the  $I_{CC}$  graphs up or down to estimate the  $I_{CC}$  requirements for a particular design.



#### **ENDURANCE CHARACTERISTICS**

The PALCE22V10 is manufactured using AMD's advanced Electrically Erasable process. This technology uses an EE cell to replace the fuse link used in bipolar

parts. As a result, the device can be erased and reprogrammed—a feature which allows 100% testing at the factory.

## **Endurance Characteristics**

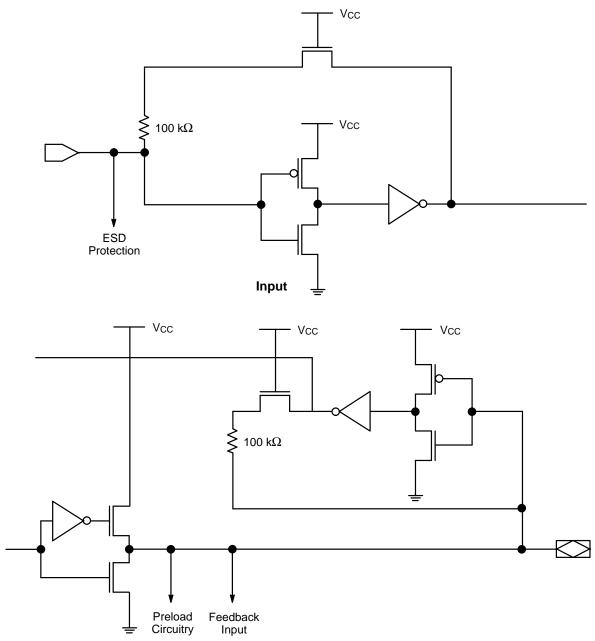
Symbol	Parameter	Test Conditions	Min	Unit
tor	Min Pattern Data Retention Time	Max Storage Temperature	10	Years
N	Min Reprogramming Cycles	Normal Programming Conditions	100	Cycles

# **Bus-Friendly Inputs**

The PALCE22V10H-15/25, Q-25 (Com'l) and H-20 (Ind) inputs and I/O loop back to the input after the second stage of the input buffer. This configuration reinforces the state of the input and pulls the voltage away from the

input threshold voltage. Unlike a pull-up, this configuration cannot cause contention on a bus. For an illustration of this configuration, see the input/output equivalent schematics.

# INPUT/OUTPUT EQUIVALENT SCHEMATICS FOR SELECTED /4 DEVICES\*



16564D-15

Device	Rev Letter
PALCE22V10H-15	
PALCE22V10H-20	Н
PALCE22V10H-25	
PALCE22V10Q-25	I

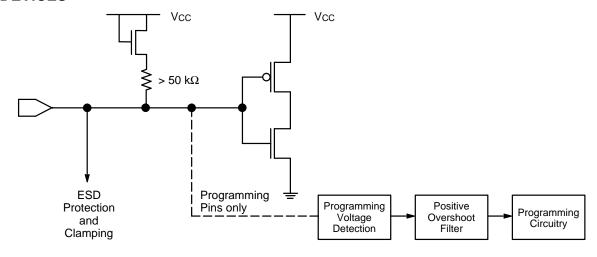
Output

#### **ROBUSTNESS FEATURES**

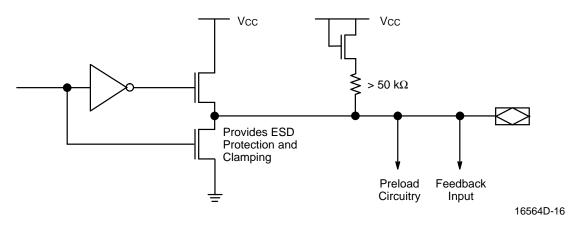
The PALCE22V10X-X/5 devices have some unique features that make them extremely robust, especially when operating in high-speed design environments. Pull-up resistors on inputs and I/O pins cause unconnected pins to default to a known state. Input clamping circuitry limits negative overshoot, eliminating the

possibility of false clocking caused by subsequent ringing. A special noise filter makes the programming circuitry completely insensitive to any positive overshoot that has a pulse width of less than about 100 ns for the /5 version. Selected /4 devices are also being retrofitted with these robustness features. See the chart below for device listing.

# INPUT/OUTPUT EQUIVALENT SCHEMATICS FOR /5 VERSION AND SELECTED /4 DEVICES\*



**Typical Input** 



**Typical Output** 

Device	Rev Letter
PALCE22V10H-15	D
PALCE22V10H-25	D
PALCE22V10Q-25	F

#### Topside Marking:

AMD CMOS PLD's are marked on top of the package in the following manner:

**PALCEXXXX** 

Datecode (3 numbers) Lot ID (4 characters)--(Rev Letter)

The Lot ID and Rev Letter are separated by two spaces.



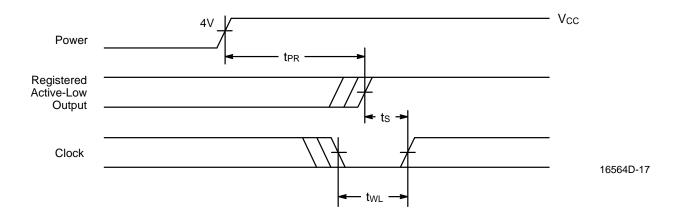
# **POWER-UP RESET**

The power-up reset feature ensures that all flip-flops will be reset to LOW after the device has been powered up. The output state will depend on the programmed pattern. This feature is valuable in simplifying state machine initialization. A timing diagram and parameter table are shown below. Due to the synchronous operation of the power-up reset and the wide range of ways

Vcc can rise to its steady state, two conditions are required to ensure a valid power-up reset. These conditions are:

- The V<sub>CC</sub> rise must be monotonic.
- Following reset, the clock input must not be driven from LOW to HIGH until all applicable input and feedback setup times are met.

Parameter Symbol	Parameter Description	Max	Unit	
tpr	Power-up Reset Time	1000	ns	
ts	Input or Feedback Setup Time	See Switching		
tw∟	Clock Width LOW	Characteristics		



**Power-Up Reset Waveform** 

# TYPICAL THERMAL CHARACTERISTICS PALCE22V10/4 (PALCE22V10H-15)

Measured at 25°C ambient. These parameters are not tested.

Parameter			Ty	/p	
Symbol	Parameter Description		SKINNYDIP	PLCC	Unit
θјс	Thermal impedance, junction to case		15	16	°C/W
$\theta$ ja	Thermal impedance, junction to ambient	ermal impedance, junction to ambient		54	°C/W
$\theta_{jma}$	Thermal impedance, junction to ambient with air flow	200 Ifpm air	67	49	°C/W
		400 Ifpm air	60	43	°C/W
		600 Ifpm air	53	37	°C/W
		800 Ifpm air	46	31	°C/W

# PALCE22V10/5 (PALCE22V10H-10)

Measured at 25°C ambient. These parameters are not tested.

Parameter			Ту	/p	
Symbol	Parameter Description		SKINNYDIP	PLCC	Unit
$\theta_{jc}$	Thermal impedance, junction to case		20	18	°C/W
$\theta$ ja	Thermal impedance, junction to ambient	ermal impedance, junction to ambient		55	°C/W
θjma	Thermal impedance, junction to ambient with air flow	200 Ifpm air	66	48	°C/W
		400 Ifpm air	61	43	°C/W
		600 Ifpm air	55	40	°C/W
		800 Ifpm air	52	37	°C/W

#### Plastic θ jc Considerations

The data listed for plastic  $\theta$  ic are for reference only and are not recommended for use in calculating junction temperatures. The heat-flow paths in plastic-encapsulated devices are complex, making the  $\theta$ jc measurement relative to a specific location on the package surface. Tests indicate this measurement reference point is directly below the die-attach area on the bottom center of the package. Furthermore, θic tests on packages are performed in a constant-temperature bath, keeping the package surface at a constant temperature. Therefore, the measurements can only be used in a similar environment.